## Product Change Notification: CENO-13HBVM813

## Date:

24-Sep-2024

## Product Category:

Interface- Infrared Products

## Notification Subject:

CCB 7011.001 Final Notice: Qualification of QMI519 as a new die attach material for MCP2122-E/SN, MCP2122T-E/SN, MCP2122-E/SNVAO and MCP2122T-E/SNVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package at MTAI assembly site.

## Affected CPNs:

**CENO-13HBVM813_Affected_CPN_09242024.pdf**
**CENO-13HBVM813_Affected_CPN_09242024.csv**

## Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of QMI519 as a new die attach material for MCP2122-E/SN, MCP2122T-E/SN, MCP2122-E/SNVAO and MCP2122T-E/SNVAO catalog part numbers (CPN) available in 8L SOIC (3.90mm) package at MTAI assembly site.

**Pre and Post Change Summary:**

|  | Pre Change | Post Change |
|---|---|---|
| Assembly Site | Microchip Technology Thailand | Microchip Technology Thailand |

| | (HQ)<br>(MTAI) | (HQ)<br>(MTAI) |
|---|---|---|
| Wire Material | Au | Au |
| Die Attach Material | 8390A | QMI519 |
| Molding Compound Material | G600V | G600V |
| Lead-Frame Material | CDA194 | A194 |
| Lead-Frame Paddle Size | 95 x158 mils | 90 x 90 mils |
| Lead-Lock | No | Yes |
| | See pre and post change for comparison. | |
| DAP Surface Prep | Ag plated | Ag selective plate |

**Note: C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.*

**Impacts to Data Sheet:**None

**Change Impact**None

**Reason for Change:**To improve manufacturability by qualifying QMI519 as a new die attach material.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**November 12, 2024 (date code: 2446)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

| | **September 2024** | | | | | **>** | **November 2024** | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|
| Workweek | 36 | 37 | 38 | 39 | 40 | | 44 | 45 | 46 | 47 | 48 |
| Qual Report Availability | | | | x | | | | | | | |
| Final PCN Issue Date | | | | x | | | | | | | |

| | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|
| Estimated Implementation Date | | | | | | | | | x | | |

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

**Revision History:**September 24, 2024: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

**PCN_CENO-13HBVM813_Pre and Post Change Summary.pdf**
**PCN_CENO-13HBVM813_Qual Report.pdf**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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